

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Continuous Reverse Voltage		V _R	40	V
Continuous Forward Current		l _F	750	mA
Forward Voltage @ I _F = 750mA		V _F	490	mV
Average Peak Forward Current; D.C. = 50%		I _{FAV}	1500	mA
Non Repetitive Forward Current	t ≤ 100μs	I _{FSM}	12	А
	t ≤ 10ms		5.2	А

Thermal Characteristics

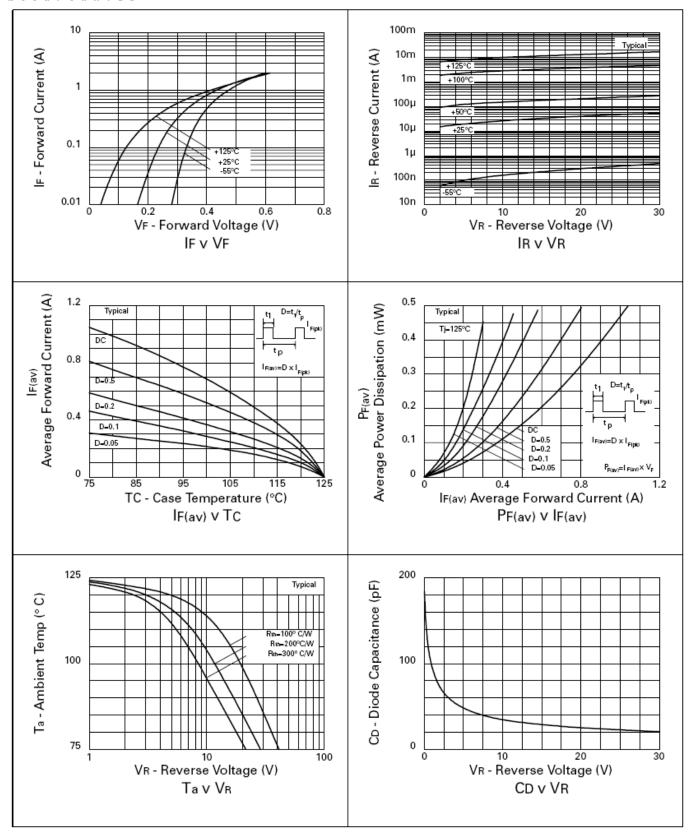
Characteristic	Symbol	Value	Unit
Power Dissipation, T _A = +25°C	P _D	500	mW
Junction Temperature	TJ	125	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

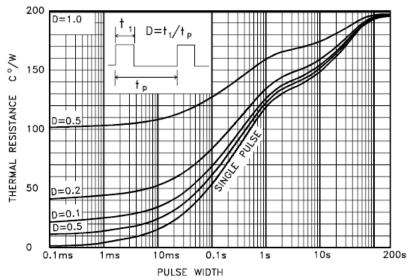
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage	V _{(BR)R}	40	60	_	V	I _R = 300μA
		_	225	280	mV	I _F = 50mA
		_	235	310		I _F = 100mA
	V _F	_	290	350		I _F = 250mA
Forward Voltage (Note 5)		_	340	420		I _F = 500mA
		_	390	490		I _F = 750mA
		_	440	540		I _F = 1A
		_	530	650		I _F = 1.5A
Reverse Current (Note 6)	I _R	_	50	100	μA	V _R = 30V
Diode Capacitance	C _D	_	25	_	pF	f = 1MHz, V _R = 25V
Reverse Recovery Time	Trr	_	12	_	ns	Switched from I_F = 500mA to I_R = 500mA Measured @ I_R = 50mA

5. Measured under pulsed conditions. Pulse width = 300μ S. Duty cycle $\leq 2\%$. 6. Short duration pulse test used to minimize self-heating effect. Notes:





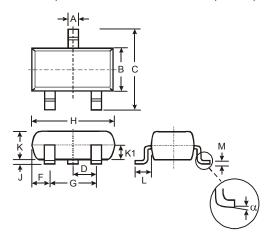




MAXIMUM TRANSIENT THERMAL RESISTANCE*

Package Outline Dimensions

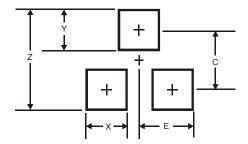
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23				
Dim	Min	Max	Тур	
Α	0.37	0.51	0.40	
В	1.20	1.40	1.30	
С	2.30	2.50	2.40	
D	0.89	1.03	0.915	
F	0.45	0.60	0.535	
G	1.78	2.05	1.83	
Н	2.80	3.00	2.90	
J	0.013	0.10	0.05	
K	0.903	1.10	1.00	
K1	-	-	0.400	
L	0.45	0.61	0.55	
М	0.085	0.18	0.11	
α	0°	8°	-	
All Dimensions in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Υ	0.9
С	2.0
E	1.35

^{*} Reference above figure, devices were mounted on a 15mmx15mm ceramic substrate.



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